

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







3M[™] Mini-Clamp Socket

2 mm, Surfacemount, Right Angle



- Low profile design minimizes overall thickness
- Compact design saves board space
- Multiple PCB locating post layouts to ensure competitive compatibility
- Solder tab design helps ensures a reliable solder joint
- Mating Latch feature provides a reliable interconnection in demanding applications
- High number of mating cycles (300)
- Maximum current rating of 3 Amps
- Dust cover accessory available for use in harsh environment
- Available in Tape and Reel
- RoHS Compliant. See the Regulatory Information Appendix (RIA) in the "RoHS compliance" section of www.3Mconnector.com for compliance information (RIA E1 & C1 apply)

Date Modified: July 14, 2011

TS-2271-C Sheet 1 of 4

Physical

Insulation:

Material: LCP Flammability: UL 94V-0

Color: Black

Contact:

Material: Copper Alloy

Plating:

Underplating: 100 µ" [2.54 µm) Ni

Wiping Area: 0.2 μm [8 μ"] min Gold with Lubricant

Solder Tails: Gold Flash

Solder Tabs: 120 μ" min [3 μm min) Matte Sn over 40 μ"-120 μ" [1-3 μm] Ni

Marking: 3M Logo, Position Indicator, Insulator Material

Mating Compatibility: 371 Series

Electrical

Current Rating: 3.0 A Voltage Rating: 32 V

Insulation Resistance: $1,000 \text{ M}\Omega$ minimum at 500 V_{DC}

Withstanding Voltage: 1,000 V_{RMS} for 1 minute

Environmental

Temperature Rating: -20°C to +85°C ambient (1.0 A max.)

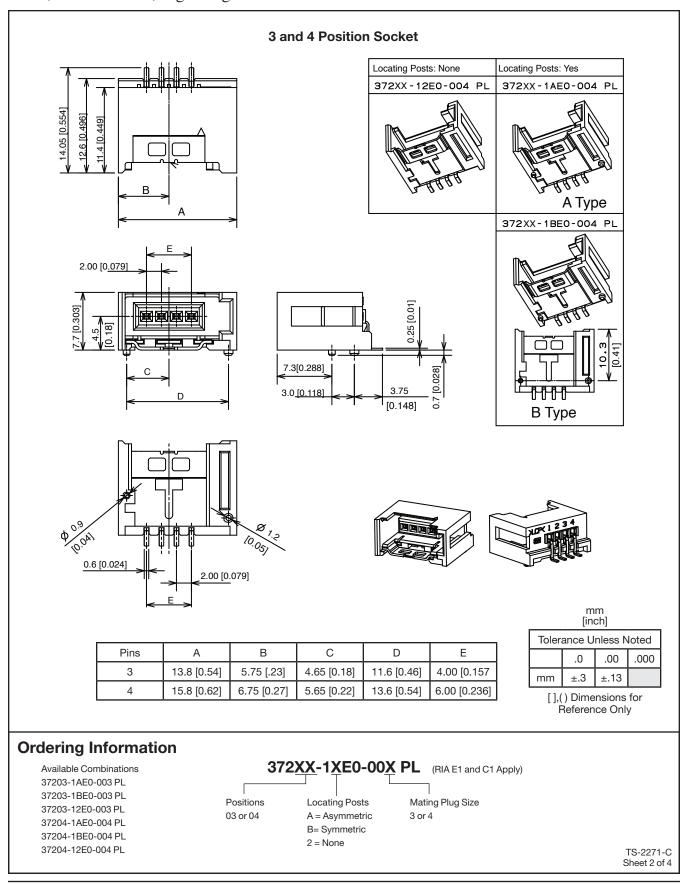
-20°C to +75°C ambient (2.0 A max.) -20°C to +60°C ambient (3.0 A max.) (Note: UL rating is 65 C at 3.0 A, 32 V)

Process Rating: 260°C max. SMT reflow (J-STD-020 MSL1)

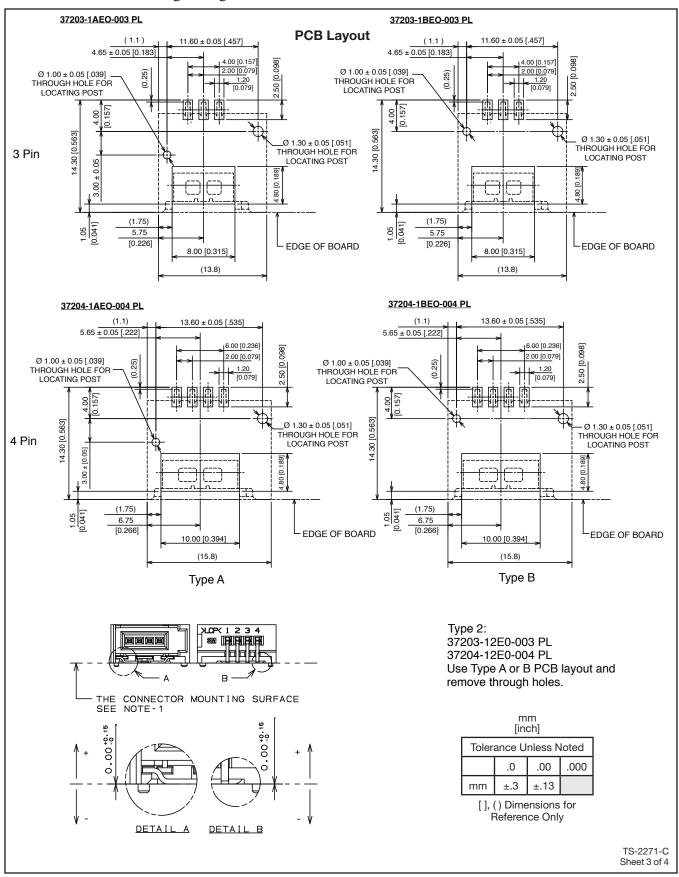
390°C max. for soldering iron

UL File No.: E68080

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